

WLCSP11, 2.05x1.44 CASE 567BN-01 **ISSUE O** 

**DATE 26 JUL 2010** 

## NOTES:

- NO LES:

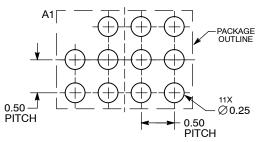
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.56	0.72		
A1	0.21	0.27		
A2	0.42 REF			
b	0.29	0.35		
D	2.05 BSC			
E	1.44 BSC			
е	0.50 BSC			

## **RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SCALE 4:1					
PIN A1 REFERENCE  E					
2X					
OptiGuard Option — A2					
// 0.05 C					
NOTE 3 A1 SIDE VIEW C SEATING PLANE					
11X Ø b  0.05 C A B C  0.03 C  B  1 2 3 4					
BOTTOM VIEW					

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